

The IEEE International Symposium on Circuits and Systems (ISCAS) is the flagship conference of the IEEE Circuits and Systems Society and the world's premiere forum for researchers in the active fields of theory, design and implementation of circuits and systems. ISCAS 2024 will be held in Singapore, from May 19 to 22, 2024. ISCAS 2024 is inspired by the theme "Circuits and Systems for Sustainable Development", which is perfectly aligned with the host city Singapore's goal. This symposium will include technical oral lectures and poster sessions, special sessions, tutorials, live demonstrations and workshops, ranging from various topics in circuits and systems.

Participation in tutorials and technical meetings is an excellent opportunity for lifelong learning, and ISCAS 2024 is committed to supporting your professional development. Continuing Education Units (CEUs) will be available for ISCAS delegates participating in tutorials or attending technical sessions.

Suitable tutorial topics range from emerging research areas to established techniques of practical and industrial relevance within the scope of the Circuits and Systems Society.

Tutorial Proposals Submission Guidelines

Please submit tutorial proposals by email to the Tutorial Co-Chairs Massimo Alioto (massimo.alioto@gmail.com), Elena Blokhina (elena.blokhina@ucd.ie), and Francois Rivet (francois.rivet@ims-bordeaux.fr) by Oct 15, 2023. The proposal should include a two-page (maximum) description of the tutorial and one-page professional biographies of the tutorial speakers that highlight their qualifications and track records in the proposed subject area. The proposal needs to contain the following information:

1. Format of the Tutorial

Full-day or Half-day.

2. Title and Abstract

Propose a title and an abstract that allows conference attendees to quickly and accurately understand the subject matter of the tutorial.

3. Motivation and Focus

Explain why your topic is important to the ISCAS community and what you hope the participants will learn by attending your tutorial. Please provide a syllabus outlining the contents of the tutorial and the learning outcomes. This syllabus should be realistic, given the time available.

(e.g., morning lectures: fundamentals and case studies; afternoon panel discussion or brainstorming sessions, etc.).

Important Dates:

Tutorials Proposals: Oct 15, 2023 **Tutorials Proposals Notification:** Nov 15, 2023 Submission of Final Tutorial Slides: Apr 15, 2024 Hands-off ready: Apr 30, 2024



2024.ieee-iscas.org

Some tutorials may feature different speakers that should be advertised, but it is neither necessary nor a requirement. For instance, a full-day tutorial may have, at most, four different speakers, while a half-day tutorial could have up to two speakers. If you plan to have multiple speakers, please provide their names and affiliations and clearly describe the parts of the tutorial that they will cover.

5. Basic Structure of the Tutorial

4. List of Speakers

Please describe your use of the time available.

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